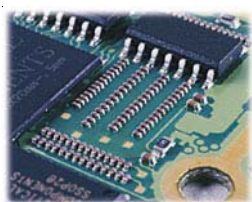


## LEAD-FREE PASTE REMOVER

JNJ Industries' GlobalTech® Lead-Free Paste Remover is a safe, low cost cleaner for high tack, difficult to clean, lead free solder paste and flux materials. It is equally effective on no-clean and water soluble Pb free pastes, and for general cleaning of all types of solder pastes, even those containing lead and other metals. It works quickly to remove tough organic contaminants such as soldering oils, waxes and other similar soils found in electronic assembly manufacturing. Excellent for cleaning printing stencils, squeegees, screens, equipment, and for misprinted



PC boards. Lead-Free Paste Remover dries at the right speed to enable complete cleaning without slowing down production. Some chemistries dry too fast, not staying around long enough to do a thorough job, while others dry too slow so that require additional time or materials to

keep production moving. Lead-Free Paste Remover dries fast, leaves no residue, and does not require rinsing.

### Method of Use:

Benchtop use, brush, wipe, or spray, products may be dipped or immersed. Should be used at room temperature, do not elevate temperature above the flash point. Not for vapor condensation cleaning.

### Environmental:

- Not a Hazardous Air Pollutant (HAP)
- CFC and HCFC Free
- Not regulated by the Clean Air Act (CAA)
- Not implicated in global warming
- SNAP (Significant New Alternatives Policy) approved
- Not reportable under SARA 313
- All ingredients are listed in the TSCA Inventory - Toxic Substance Control Act
- Low Toxicity



Offered in convenient packaging styles: 100-count saturated wipes, Foil Refill Packs (FRP's), spray bottles, gallons, & drums.

### Applications:

- Screens & stencils
- Good for stencil cleaning machines
- General degreasing
- Misprinted circuit boards
- Production equipment (stencil printers)
- Removes organic contaminants such as soldering oils, waxes, silicones, uncured adhesives and other difficult soils

**Dries to Zero Residue...No Rinsing Required  
Completely Water Soluble**

BOILING POINT approx.	FLASH PT °F est.	% VOLATILE	VAPOR DENSITY	VAPOR PRESSURE mm mercury	SPECIFIC GRAVITY 7.33 lb/gal	EVAPORATION RATE BuAc=1	SOLUBILITY IN WATER	VOC lb/gal
202° F	75°	100	ND	<20	0.88	0.94	100	4.86

**HAZARD RATING:** Fire: 3, Toxicity: 1, Reactivity: 0 **HAZARD CLASS:** Flammable Liquid